



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-02-12</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ED6S*T85116Y	A	BO2A	2014-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
65.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5X4.4X0.9	15	gull wing	
Comment	Package: TSSOP 16 BODY 4.4 PITCH 0.65			

0		
Query		Response
Product(s) meets EU RoHS requirement without any exemptions		true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Product(s) is obsolete, no information is available		false
Product(s) is unknown, no information is available		false
Exemption Id.	Description	

0				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ED6S*T85116Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.058	mg	supplier	die	Silicon (Si)	7440-21-3		1.028	mg	971645	18932
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	7561	147
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	3781	74
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.018	mg	17013	331
Leadframe	Copper & its alloys	29.228	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.173	mg	998118	537256
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.013	mg	445	239
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	855	460
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.016	mg	547	295
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	34	18
Die attach	Other Organic Materials	0.368	mg	supplier	glue	Silver (Ag)	7440-22-4		0.279	mg	758152	5138
Die attach				supplier	glue	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.037	mg	100543	681
Die attach				supplier	glue	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.015	mg	40761	276
Die attach				supplier	glue	2,6-Diglycidyl phenyl allyl ether	CE 417-470-1		0.022	mg	59783	405
Die attach				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.015	mg	40761	276
Bonding wire	Other inorganic materials	0.318	mg	supplier	wire	Gold (Au)	7440-57-5		0.318	mg	1000000	5856
encapsulation	Other Organic Materials	34.028	mg	supplier	mold compound	Amorphous silica	7631-86-9		27.222	mg	799988	501326
encapsulation				supplier	mold compound	epoxy resin	Proprietary		5.615	mg	165011	103407
encapsulation				JIG I	mold compound	Brominated flame retardant	Proprietary		0.34	mg	9992	6262
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.681	mg	20013	12541
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.17	mg	4996	3131